



FGA25N120FTD

1200V, 25A Field Stop Trench IGBT

Features

- Field stop trench technology
- High speed switching
- Low saturation voltage: $V_{CE(sat)} = 1.6V @ I_C = 25A$
- High input impedance
- RoHS complaint

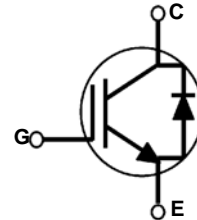
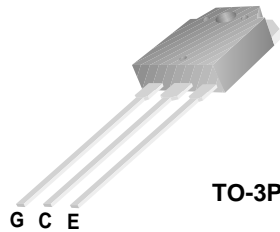
Applications

- Induction heating and Microwave oven
- Soft switching applications



General Description

Using advanced field stop trench technology, Fairchild's 1200V trench IGBTs offer superior conduction and switching performances, and easy parallel operation with exceptional avalanche ruggedness. This device is designed for soft switching applications.



Absolute Maximum Ratings

Symbol	Description	Ratings	Units
V_{CES}	Collector to Emitter Voltage	1200	V
V_{GES}	Gate to Emitter Voltage	± 25	V
I_C	Collector Current @ $T_C = 25^\circ C$	50	A
	Collector Current @ $T_C = 100^\circ C$	25	A
$I_{CM} (1)$	Pulsed Collector Current	75	A
I_C	Diode continuous Forward current @ $T_C = 100^\circ C$	25	A
P_D	Maximum Power Dissipation @ $T_C = 25^\circ C$	313	W
	Maximum Power Dissipation @ $T_C = 100^\circ C$	125	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ C$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ C$

Notes:
1: Repetitive: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.4	$^\circ C/W$
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.42	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	$^\circ C/W$

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Type	Qty per Tube	Max Qty per Box
FGA25N120FTD	FGA25N120FTDTU	TO-3PN	-	-	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
V_{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	1200	-	-	V
I_{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	1	mA
I_{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±250	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 25mA, V_{CE} = V_{GE}$	3.5	6	7.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 25A, V_{GE} = 15V$	-	1.6	2	V
		$I_C = 25A, V_{GE} = 15V, T_C = 125°C$	-	1.88	-	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V, f = 1MHz$	-	3830	-	pF
C_{oes}	Output Capacitance		-	130	-	pF
C_{res}	Reverse Transfer Capacitance		-	86	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600V, I_C = 25A, R_G = 15Ω, V_{GE} = 15V, \text{Inductive Load}, T_C = 25°C$	-	48	-	ns
t_r	Rise Time		-	96	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	210	-	ns
t_f	Fall Time		-	215	-	ns
E_{on}	Turn-On Switching Loss		-	0.34	-	mJ
E_{off}	Turn-Off Switching Loss		-	0.90	1.20	mJ
E_{ts}	Total Switching Loss	-	1.24	-	mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600V, I_C = 25A, R_G = 15Ω, V_{GE} = 15V, \text{Inductive Load}, T_C = 125°C$	-	44	-	ns
t_r	Rise Time		-	113	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	232	-	ns
t_f	Fall Time		-	390	-	ns
E_{on}	Turn-On Switching Loss		-	0.38	-	mJ
E_{off}	Turn-Off Switching Loss		-	1.39	-	mJ
E_{ts}	Total Switching Loss	-	1.77	-	mJ	
Q_g	Total Gate Charge	$V_{CE} = 600V, I_C = 25A, V_{GE} = 15V$	-	160	-	nC
Q_{ge}	Gate to Emitter Charge		-	30	-	nC
Q_{gc}	Gate to Collector Charge		-	78	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Units	
V _{FM}	Diode Forward Voltage	I _F = 25A	T _C = 25°C	-	1.4	1.8	V
			T _C = 125°C	-	1.42	-	
t _{rr}	Diode Reverse Recovery Time		T _C = 25°C	-	770	-	ns
			T _C = 125°C	-	895	-	
I _{rr}	Diode Reverse Recovery Time	I _{ES} = 25A, dI _{ES} /dt = 200A/μs	T _C = 25°C	-	48	-	A
			T _C = 125°C	-	50	-	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C	-	18	-	μC
			T _C = 125°C	-	23	-	

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

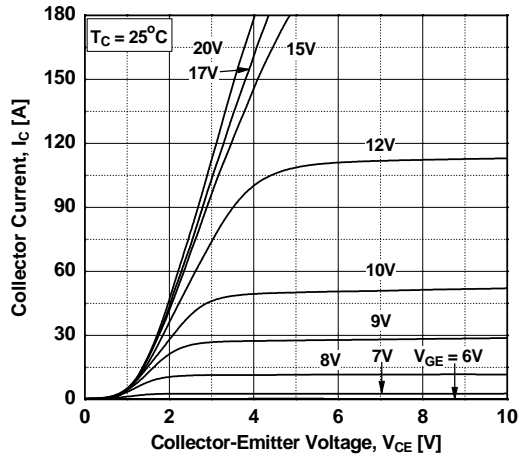


Figure 2. Typical Output Characteristics

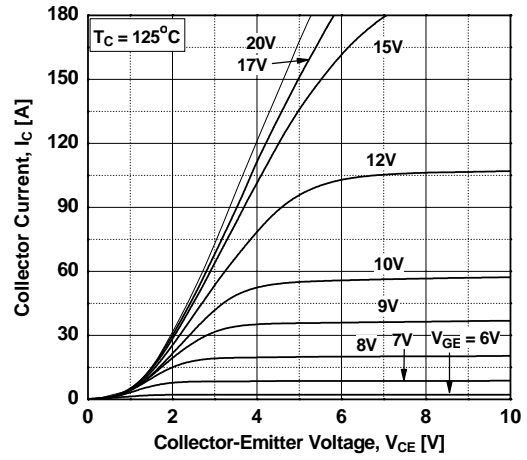


Figure 3. Typical Saturation Voltage Characteristics

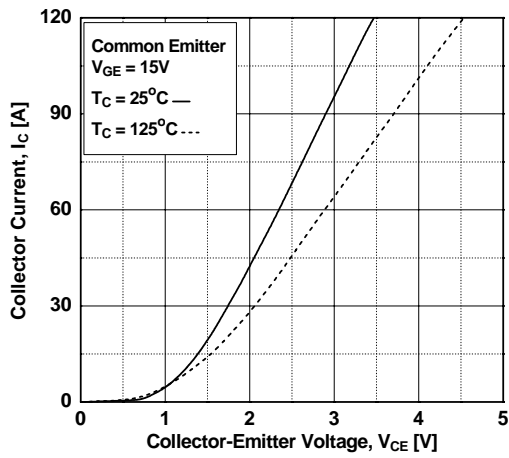


Figure 4. Transfer Characteristics

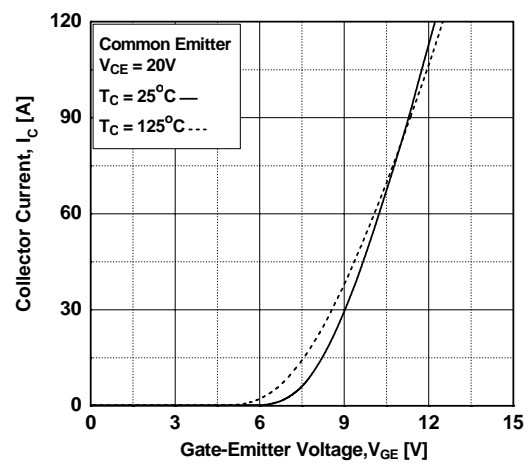


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

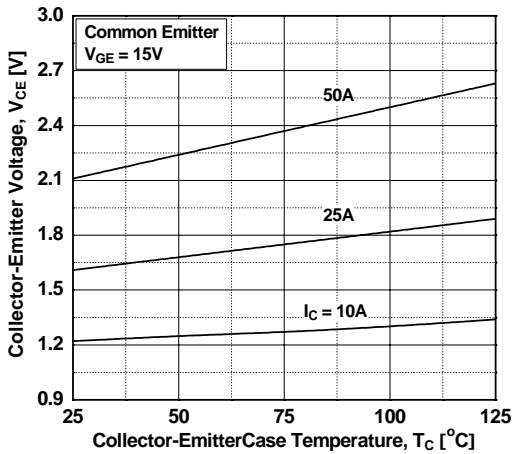
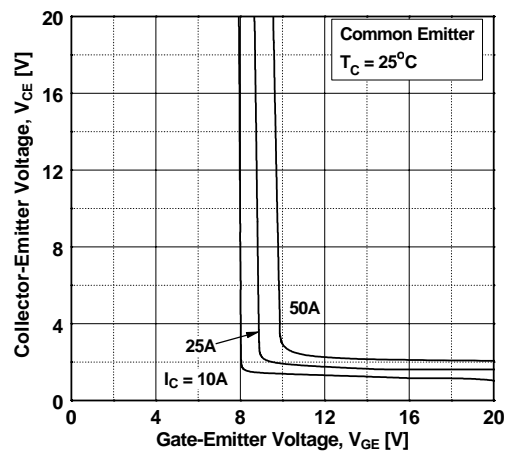


Figure 6. Saturation Voltage vs. Vge



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. V_{GE}

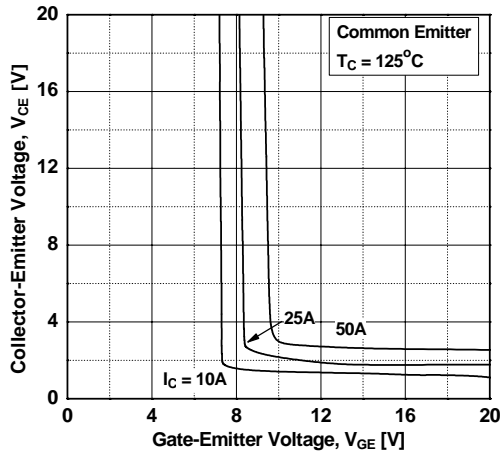


Figure 8. Capacitance Characteristics

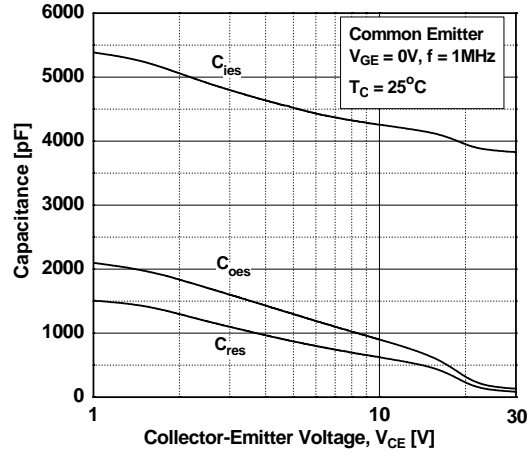


Figure 9. Gate charge Characteristics

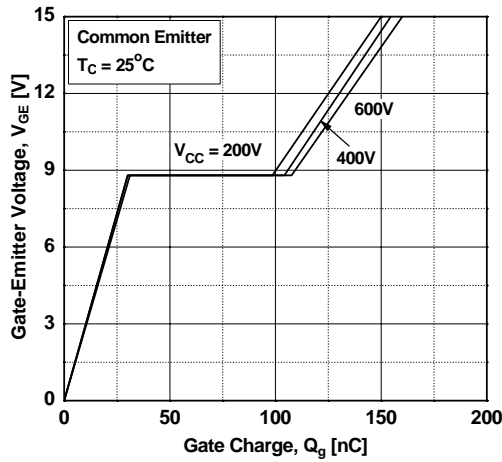


Figure 10. SOA Characteristics

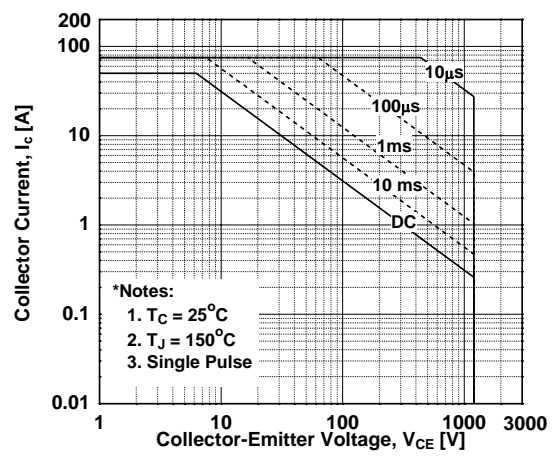


Figure 11. Turn-on Characteristics vs. Gate Resistance

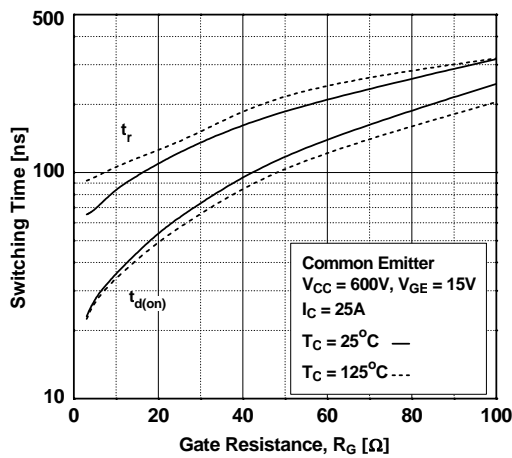
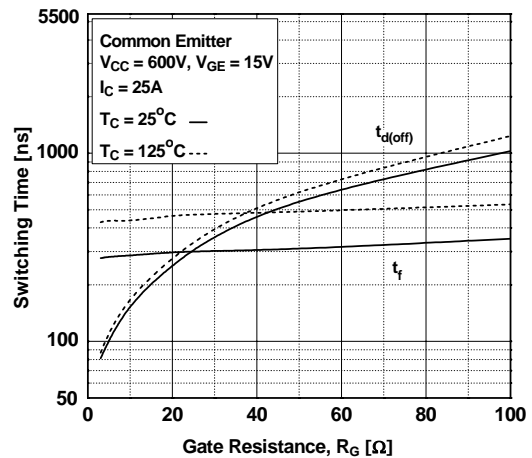


Figure 12. Turn-off Characteristics vs. Gate Resistance



Typical Performance Characteristics

Figure 13. Turn-on Characteristics vs. Collector Current

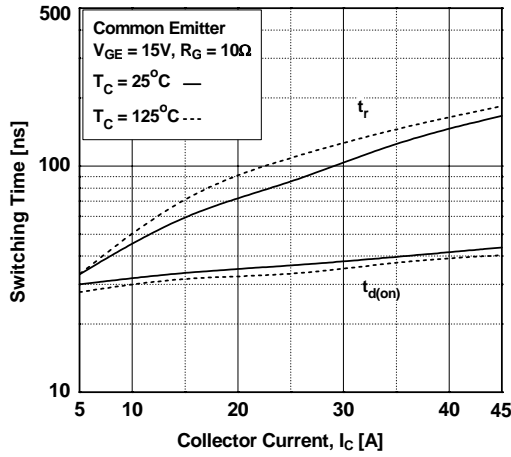


Figure 14. Turn-off Characteristics vs. Collector Current

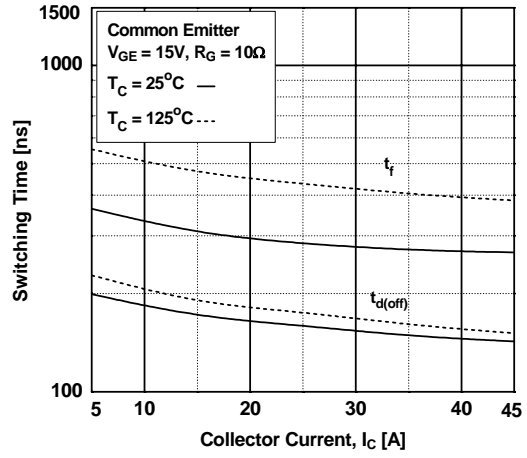


Figure 15. Switching Loss vs. Gate Resistance

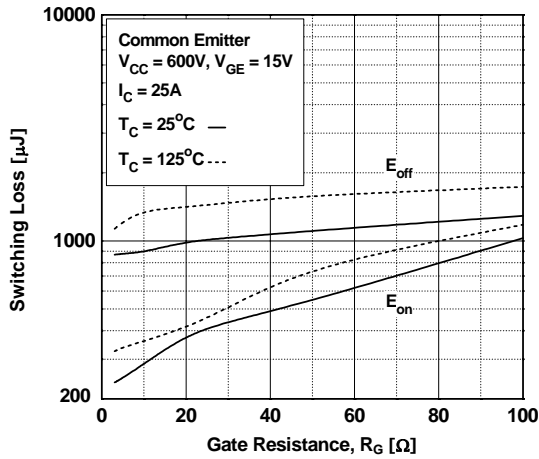


Figure 16. Switching Loss vs. Collector Current

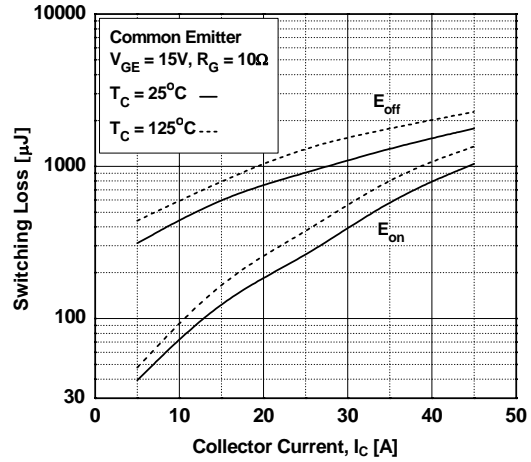


Figure 17. Turn off Switching SOA Characteristics

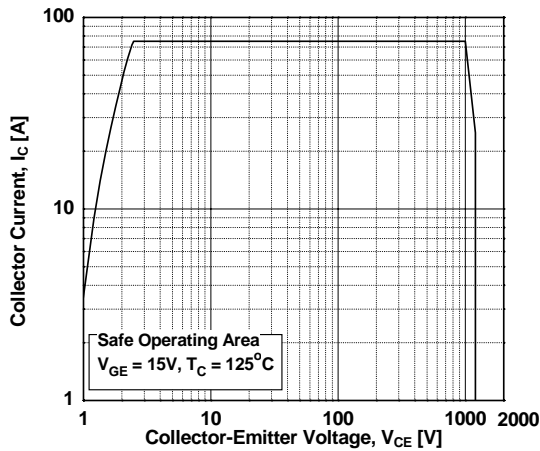
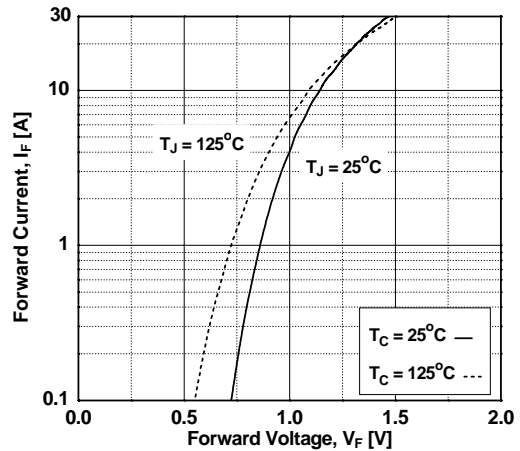


Figure 18. Forward Characteristics



Typical Performance Characteristics

Figure 19. Reverse Recovery Current

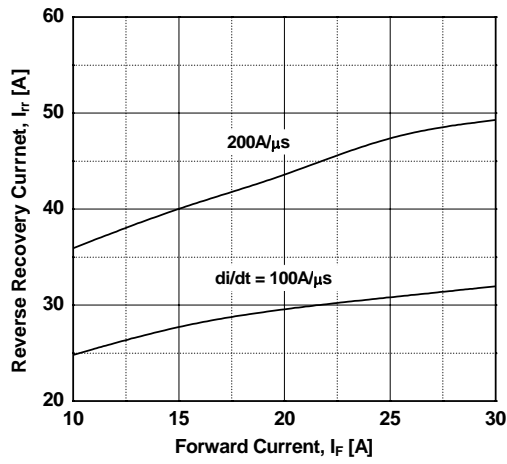


Figure 20. Stored Charge

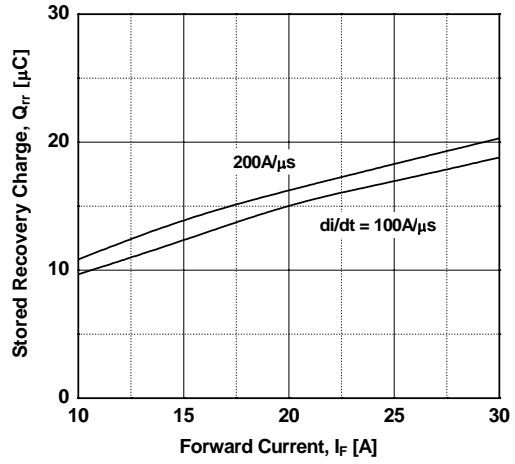


Figure 21. Reverse Recovery Time

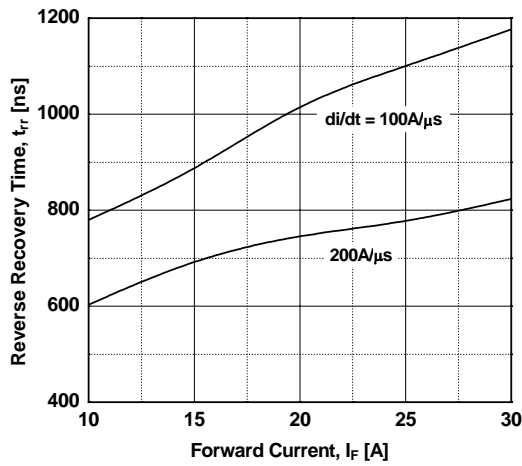
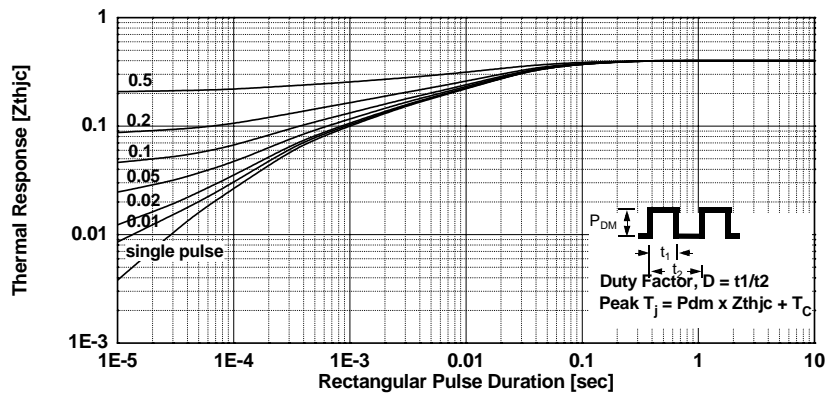
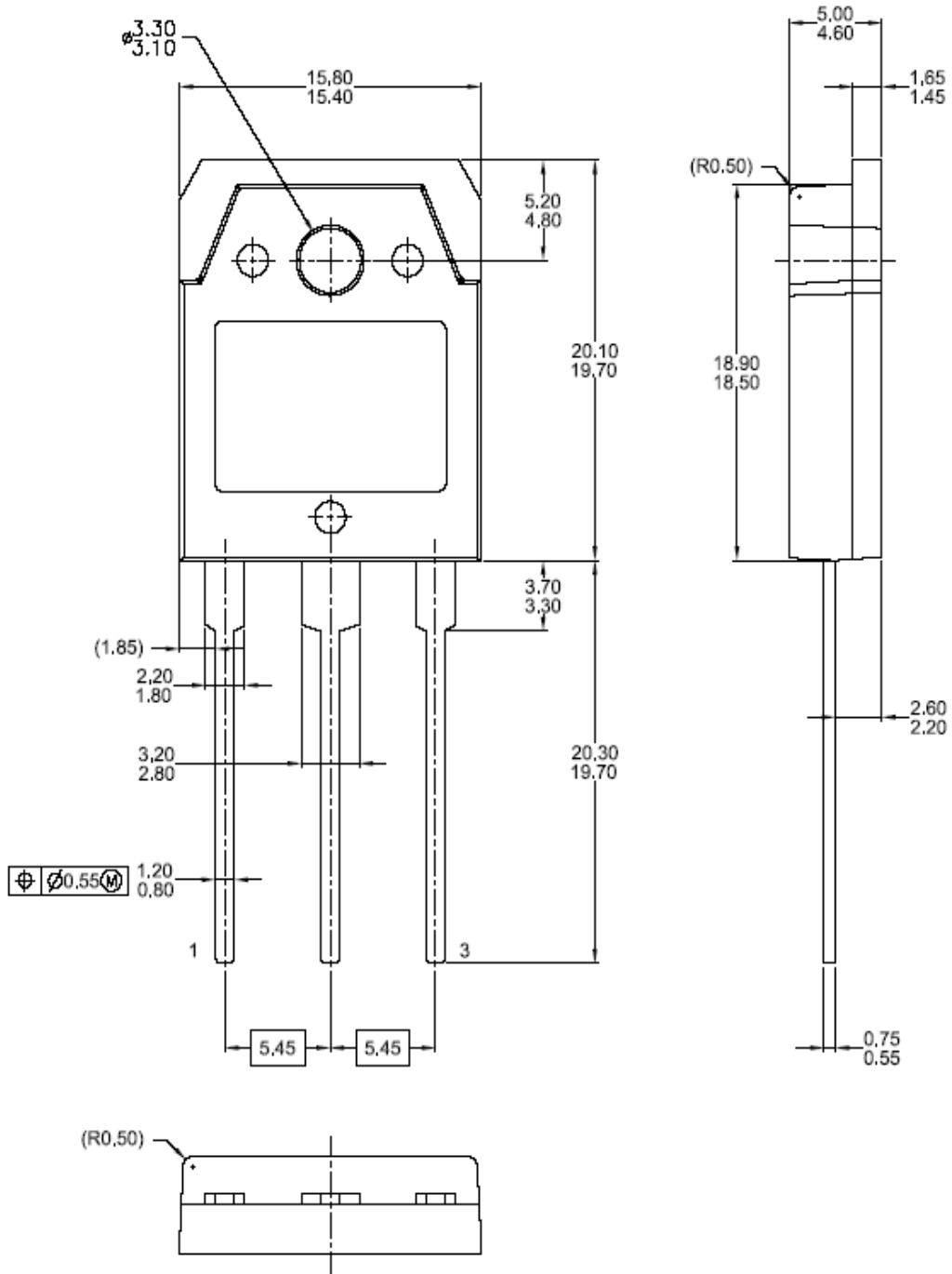


Figure 22. Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-3PN






Dimensions in Millimeters



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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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